

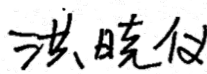
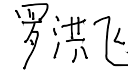
PRODUCT SPECIFICATION

CDTECH Model: **S070QWS168HD-DC187**

CUSTOMER Model: **-**

Description: **7.0 " TFT-LCD Module with CTP**

Version: **1.0**

CDTECH	PREPARED BY	CHECKED BY	APPROVED BY
SIGNATURE			
DATE	2025.8.27	2025.8.27	2025.8.27

CUSTOMER APPROVAL	SIGNATURE	DATE



Record of Revisions

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1. General Specifications

1.1 LCM General Information

Item	Specification	Unit
LCD Size	7.0	inch
Number of Pixels	1024 (H) RGB x 600 (V)	pixels
Display Mode	Normally Black	-
Viewing Direction	Free	-
Interface	MIPI	-
Display Colors	16.7M	colors
Outline Dimension	240 (H) x 114 (V) x 8.42 (D)	mm
Active Area	154.21 (H) x 85.92 (V)	mm
Pixel Pitch	0.1505 (H) x 0.1432 (V)	mm
Driver IC	EK79007AD3+EK73217BCGA	-
Operation Temperature	-20~70	°C
Storage Temperature	-30~80	°C

1.2 Touch Panel Information

Item	Specification
Touch Structure	G+G
Bonding Type with LCM	Perimeter Bonding
Driver IC	GT911
Interface	I ² C
Touch Count Max	5 Points
Surface treatment	-
Surface hardness	6H
I2C slave address	0x28
Origin of coordinate	Top Left Corner

Note1: Requirements on environmental protection RoHS compliant.

2. Absolute Maximum Ratings

Item	Symbol	MIN.	MAX.	Unit	Note
Analog Supply voltage	VCC	-0.3	5.0	V	Note 1
Digital supply voltage	IOVCC	-0.3	3.6	V	Note 1

Note 1: Permanent damage may occur to the LCD module if beyond this specification.

Functional operation should be restricted to the conditions described under normal operating conditions.

3. Electrical Characteristics

3.1 Recommended Operating Condition for TFT LCD

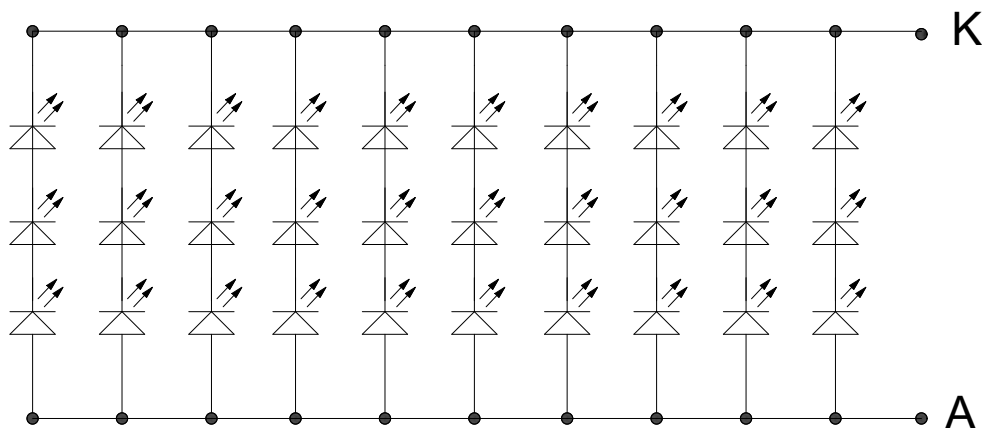
Item	Symbol	Min.	Typ.	Max.	Unit	Note
Analog Supply voltage	VCC	3.0	3.3	3.6	V	
Analog supply current	I _{VCC}	100	140	180	mA	VCC=3.3V (Red, green and blue)
Logic supply voltage	IOVCC	1.65	1.8	3.3	V	
Logic supply current	I _{IOVCC}	8	12	16	mA	IOVCC=1.8V (Red, green and blue)
Logic input voltage	V _{IH}	0.7*IOVCC	-	IOVCC	V	
	V _{IL}	GND	-	0.3*IOVCC	V	

3.2 Recommended Driving Condition for Backlight

Item	Symbol	Min.	Typ.	Max.	Unit	Note
Driving Current	I _F	-	200	-	mA	
Driving Voltage	V _F	8.1	-	10.2	V	
Power consumption	W _{BL}	1.62	-	2.04	W	
LED Life-Time	N/A	-	50,000	-	Hours	Ta=25°C Note 1

Note 1:LED lifetime is defined as the module brightness decay 50% of original brightness at Ta=25 degree, typical current.

Note 2:LED circuit :



3.3 Touch Panel

Item	Symbol	Min.	Typ.	Max.	Unit	Note
Power Supply voltage	VDD	-	3.3	-	V	
Analog supply current	I _{VDD}	-	15	-	mA	VDD=3.3V
Input high-level voltage	V _{IH}	0.7*VDD	-	VDD	V	
Input low -level voltage	V _{IL}	GND	-	0.3*VDD	V	

4. Interface Pin Assignment

4.1 LCM Pin Assignment

No.	Symbol	Description
1-2	VCC3.3V	Power supply (3.3V)
3	IOVCC1.8V	Power supply (1.8V)
4	RESET	Global reset pin
5	GND	Ground
6	D0N	MIPI Negative data signal(-)
7	D0P	MIPI Positive data signal(+)
8	GND	Ground
9	D1N	MIPI Negative data signal(-)
10	D1P	MIPI Positive data signal(+)
11	GND	Ground
12	CLKN	MIPI Negative clock signal(-)
13	CLKP	MIPI Positive clock signal(+)
14	GND	Ground
15	D2N	MIPI Negative data signal(-)
16	D2P	MIPI Positive data signal(+)
17	GND	Ground
18	D3N	MIPI Negative data signal(-)
19	D3P	MIPI Positive data signal(+)
20	GND	Ground
21	NC	No connection
22-23	GND	Ground
24	NC	No connection
25	GND	Ground
26-27	LEDK	Power for LED backlight (Cathode)
28	NC	No connection
29-30	LEDA	Power for LED backlight (Anode)

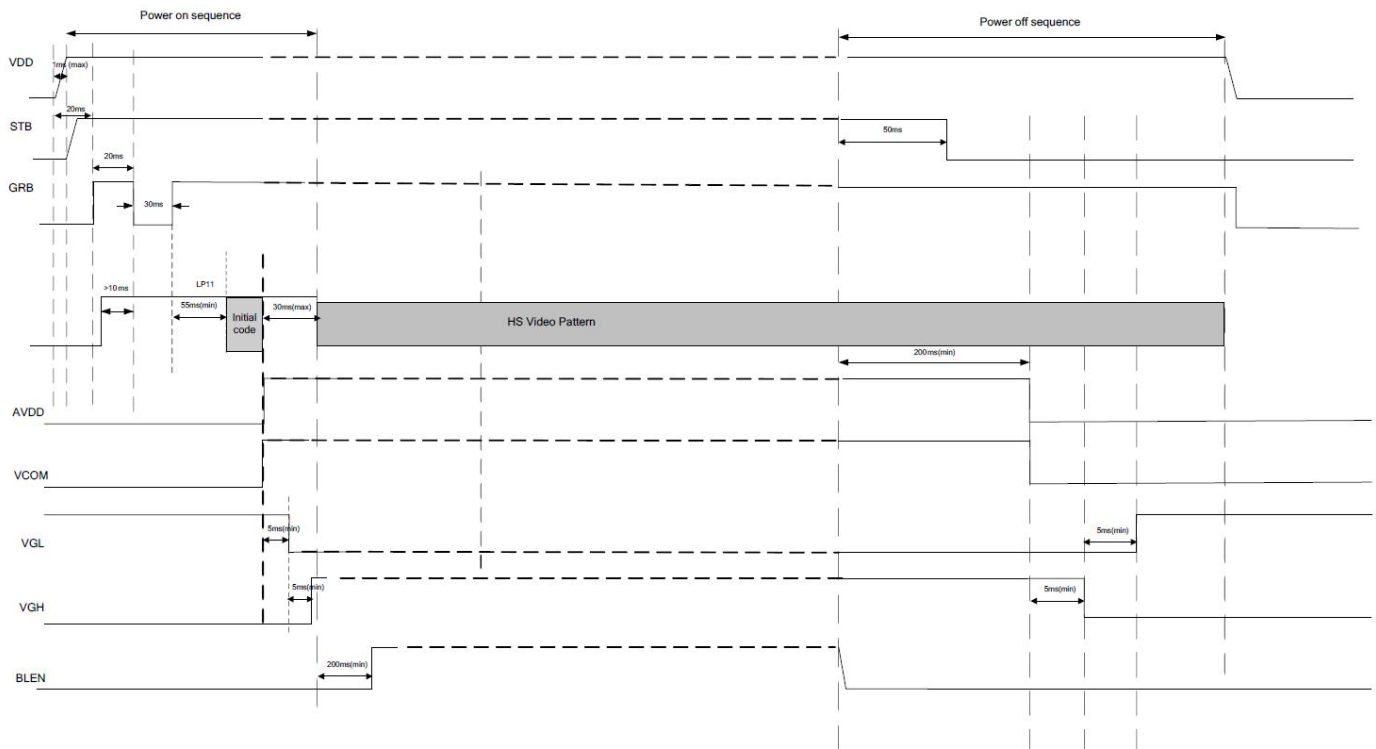
4.2 Touch FPC Pin Assignment

No.	Symbol	Description
1	GND	Ground
2	INT	Interrupt signal for CTP
3	RST	Reset Pin for CTP
4	SDA	I2C data input and output for CTP
5	SCL	I2C clock input for CTP
6	VDD	Power supply for CTP
7	VDD	Power supply for CTP
8	GND	Ground

5. Interface Characteristics

5.1 Power On/Off Sequence

In order to prevent IC from power on reset fail, the rising time (TPOR) of the digital power supply VDD should be maintained within the given specifications. Refer to “AC Characteristics” for more detail on timing.



Note: CLK and Data Lanes should keep in LP11(stop state) before GRB

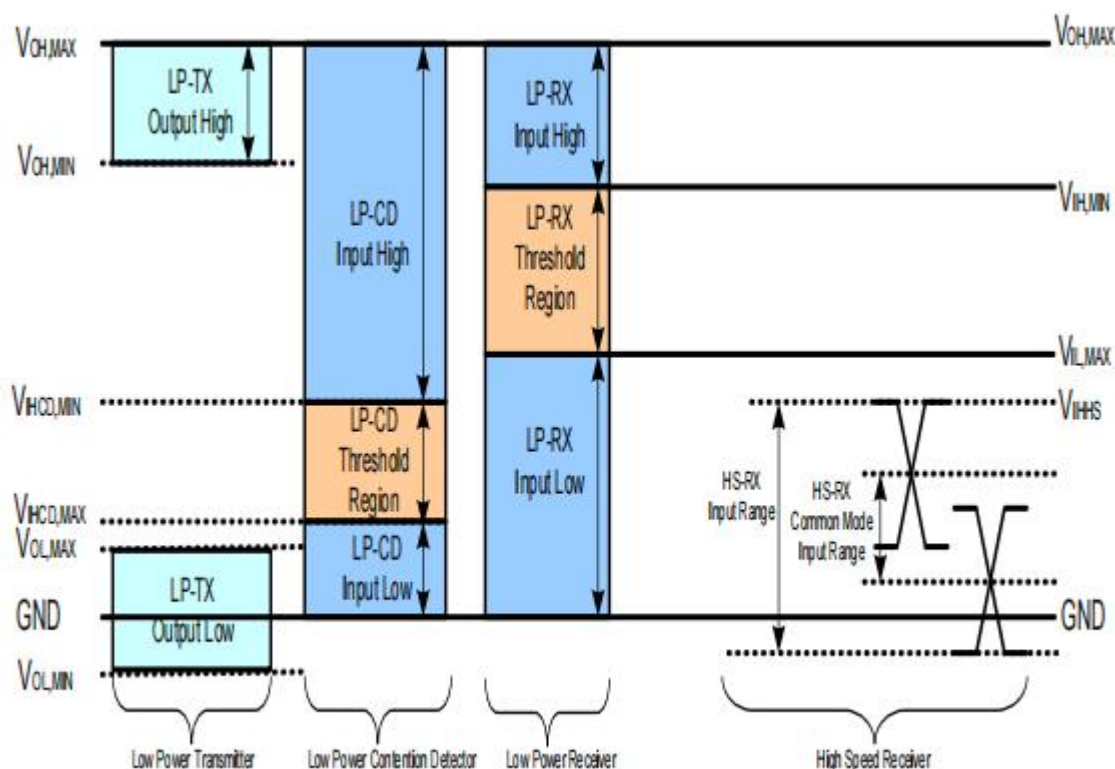
5.2 DC ELECTRICAL CHARACTERISTICS

Basic DC Characteristic

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Low level input voltage	Vil	For the digital circuit	0	-	0.3×VDD	V
High level input voltage	Vih	For the digital circuit	0.7×VDD	-	VDD	V
Input leakage current	Ii	For the digital circuit	-	-	±1	μA
High level output voltage	Voh	Ioh= -400 μA	VDD - 0.4	-	-	V
Low level output voltage	Vol	Iol= +400 μA	-	-	GND+0.4	V
Pull low/high resistor	Ri	For the digital input pin @ VDD_IF=1.8V	200K	250K	300K	ohm
Digital Operation current	Idd	Fclk=51.2MHz, VDD=VDD IF=1.8V	-	TBD	-	mA
Digital Stand-by current	Ist1	Clock and all functions are stopped	-	10	50	μA
Analog Operating Current	Idda	No load, Fclk=51.2MHz, @AVDD=13.5V, V1=13.4V, V14=0.1V	-	10	12	mA
Analog Stand-by current	Ist2	No load, clock and all functions are stopped	-	10	50	μA
Input level of V1 ~ V7	Vref1	Gamma correction voltage input	0.4*AVDD	-	AVDD-0.1	V
Input level of V8 ~ V14	Vref2	Gamma correction voltage input	0.1	-	0.6*AVDD	V
Output Voltage deviation	Vod1	Vo = AGND+0.1V ~ AGND+0.5V and Vo = AVDD-0.5V ~ AVDD-0.1V	-	±20	±35	mV
Output Voltage deviation	Vod2	Vo = AGND+0.5V ~ AVDD-0.5V	-	±15	±20	mV
Output Voltage Offset between Chips	Voc	Vo = AGND+0.5V ~ AVDD-0.5V	-	-	±20	mV
Dynamic Range of Output	Vdr	SO1 ~ 1536	0.1	-	AVDD-0.1	V
Sinking Current of Outputs	IOLy	SO1 ~ 1536; Vo=0.1V v.s 1.0V , AVDD=13.5V	80	-	-	uA
Driving Current of Outputs	IOHy	SO1 ~ 1536; Vo=13.4V v.s 12.5V , AVDD=13.5V	80	-	-	uA
Resistance of Gamma Table	Rg	Rn: Internal gamma resistor	0.7*Rn	1.0*Rn	1.3*Rn	ohm

MIPI Interface DC Characteristic

Parameter	Symbol	Min.	Typ.	Max.	Unit
MIPI Characteristics for High Speed Receiver					
Single-ended input low voltage	VILHS	-40	-	-	mV
Single-ended input high voltage	VIHHS	-	-	460	mV
Common-mode voltage	VCDRXDC	70	-	330	mV
Differential input impedance	ZID		100		ohm
HS transmit differential voltage(VOD=VDP-VDN)	VOD	140	200	250	mV
MIPI Characteristics for Low Power Mode					
Pad signal voltage range	VI	-50	-	1350	mV
Ground shift	VGNDSH	-50	-	50	mV
Logic 0 input threshold	VIL	0	-	550	mV
Logic 1 input threshold	VIH	880	-	1350	mV
Input hysteresis	VHYST	25	-	-	mV
Output low level	VOL	-50	-	50	mV
Output high level	VOH	1.1	1.2	1.3	V
Output impedance of Low Power Transmitter	ZOLP	80	100	125	ohm
Logic 0 contention threshold	VILCD,MAX	-	-	200	mV
Logic 0 contention threshold	VIHCD,MIN	450	-	-	mV

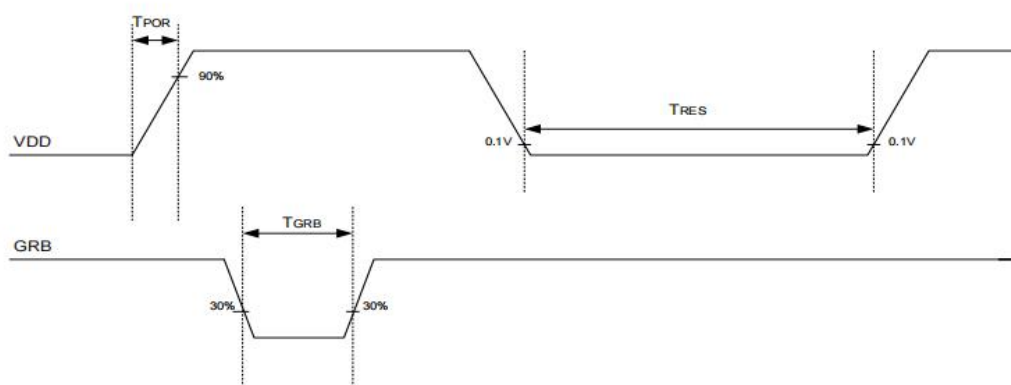


5.3 AC ELECTRICAL CHARACTERISTIC

Basic AC Characteristic

VDD/GRB AC characteristic

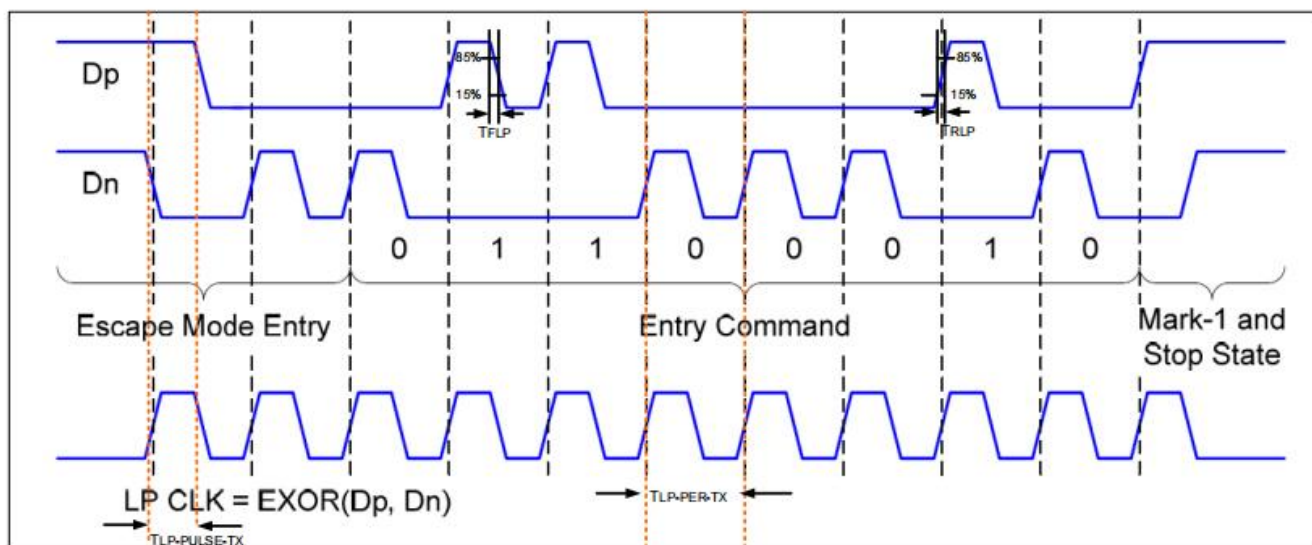
Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
VDD power slew rate	T_{POR}	-	-	20	ms	From 0 to 90% VDD
GRB active pulse width	T_{GRB}	1	-	-	ms	VDD=VDD_IF=1.8V
VDD resettle time	T_{RES}	1	-	-	s	



MIPI AC Characteristic

LP Transmitter AC Specification

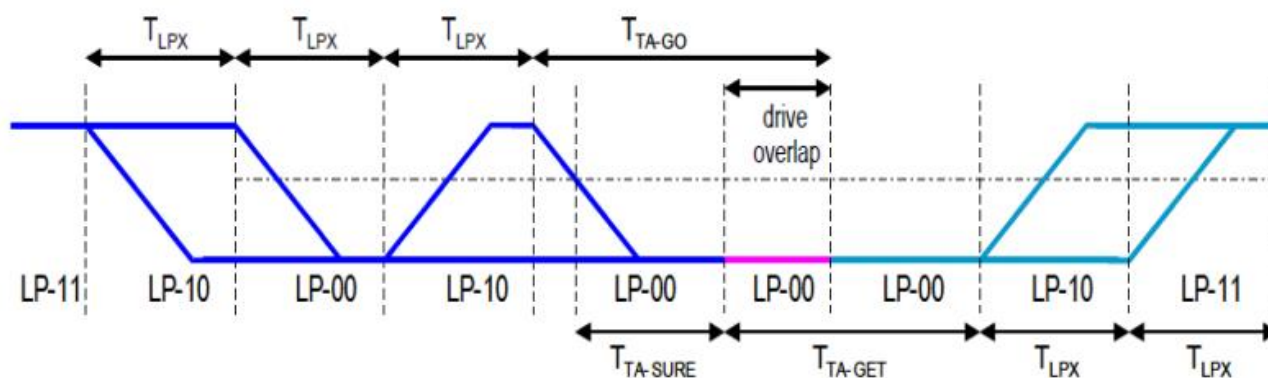
Parameter	Symbol	Min	Typ	Max	Units	Notes
15%~85% rising time and falling time	T_{RLP} / T_{FLP}	-	-	25	ns	-
30%~85% rising time and falling time	T_{REOT}	-	-	35	ns	-
Pulse width of LP exclusive-OR clock	$T_{LP-PULSE-TX}$	40	-	-	ns	-
		20	-	-	ns	-
Period of the LP EXOR clock	$T_{LP-PER-TX}$	90	-	-	mV/ns	-
Slew Rate @CLOAD =0pF	$\delta V / \delta t_{SR}$	30	-	500	mV/ns	-
Slew Rate @CLOAD =5pF		30	-	200	mV/ns	-
Slew Rate @CLOAD =20pF		30	-	150	mV/ns	-
Slew Rate @CLOAD =70pF		30	-	100	mV/ns	-
Load Capacitance	T_{RLP}	-	-	70	pF	-



Turnaround Procedure

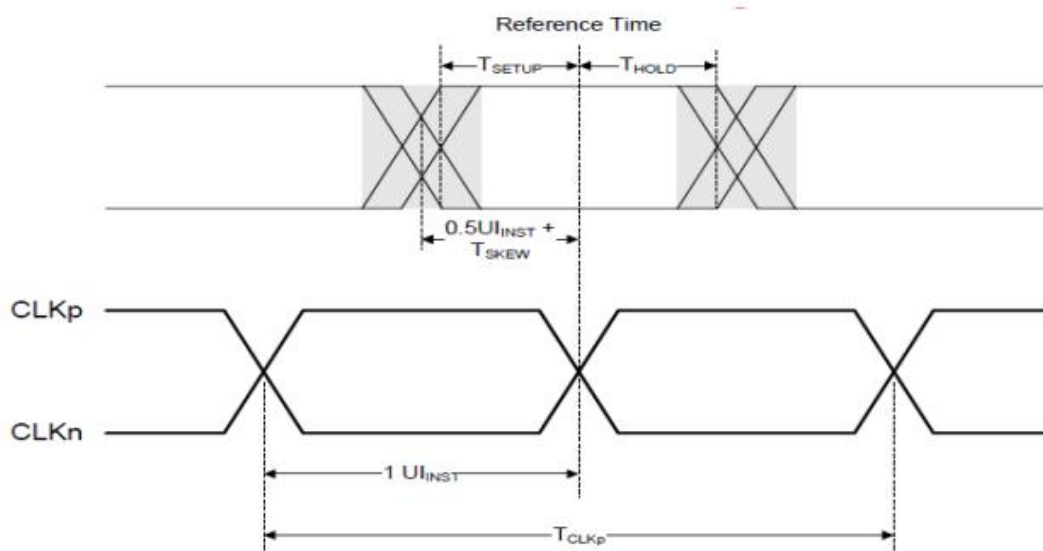
Turnaround Procedure Operation Timing Parameters

Parameter	Symbol	Min	Typ	Max	Units
Length of any Low-Power state period: Master side	T_{LPX}	50	-	75	ns
Length of any Low-Power state period: Slave side	T_{LPX}	50	55.56	58.34	ns
Ratio of T_{LPX} (Master)/ T_{LPX} (Slave) between Master and Slave side	Ratio T_{LPX}	2/3	-	3/2	
Time-out before new TX side start driving	$T_{TA-Sure}$	T_{LPX}	-	$2T_{LPX}$	ns
Time to drive LP-00 by new TX	T_{TA-GET}	-	$5T_{LPX}$	-	ns
Time to drive LP-00 after Turnaround Request	T_{TA-GO}	-	$4T_{LPX}$	-	ns



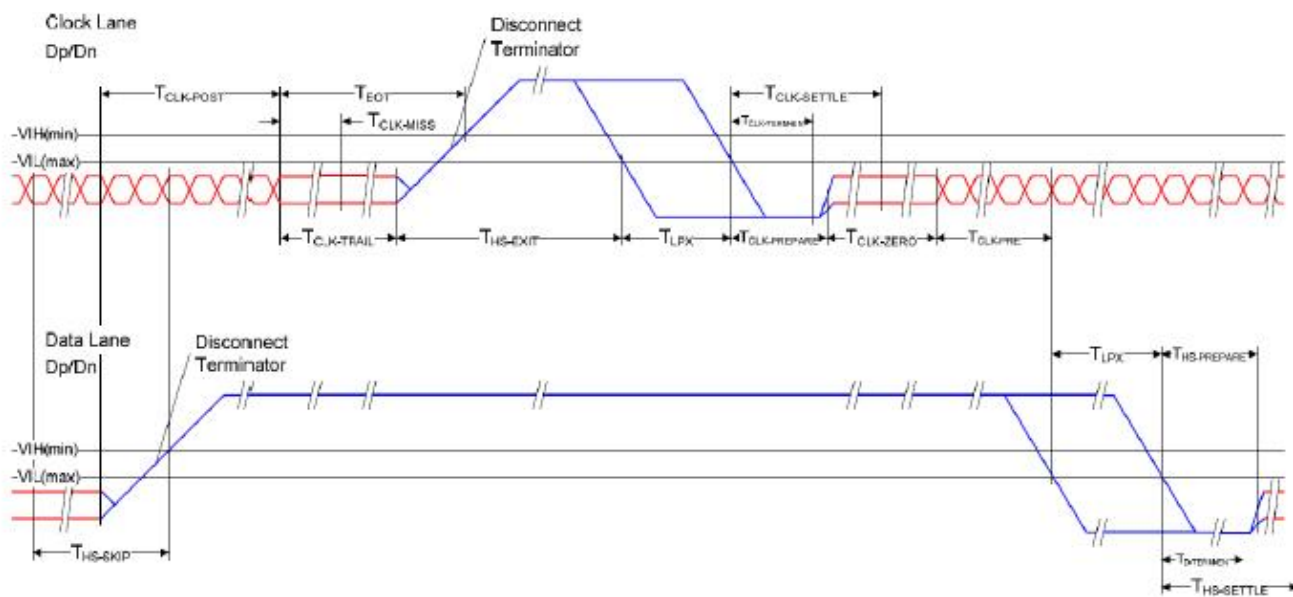
High speed transmission

Parameter	Symbol	Min	Typ	Max	Units
UI instantaneous	UI_{INST}	2	-	12.5	ns
Data to Clock Skew(measured at transmitter)	$T_{SKEW(TX)}$	-0.15	-	0.15	UI_{INST}
Data to Clock Setup time(measured at receiver)	$T_{SETUP(RX)}$	0.15	-	-	UI_{INST}
Data to Clock Hold time(measured at receiver)	$T_{HOLD(RX)}$	0.15	-	-	UI_{INST}
20%~80% rise time and fall time	T_R, T_F	150	-	-	ps
		-	-	0.3	UI_{INST}

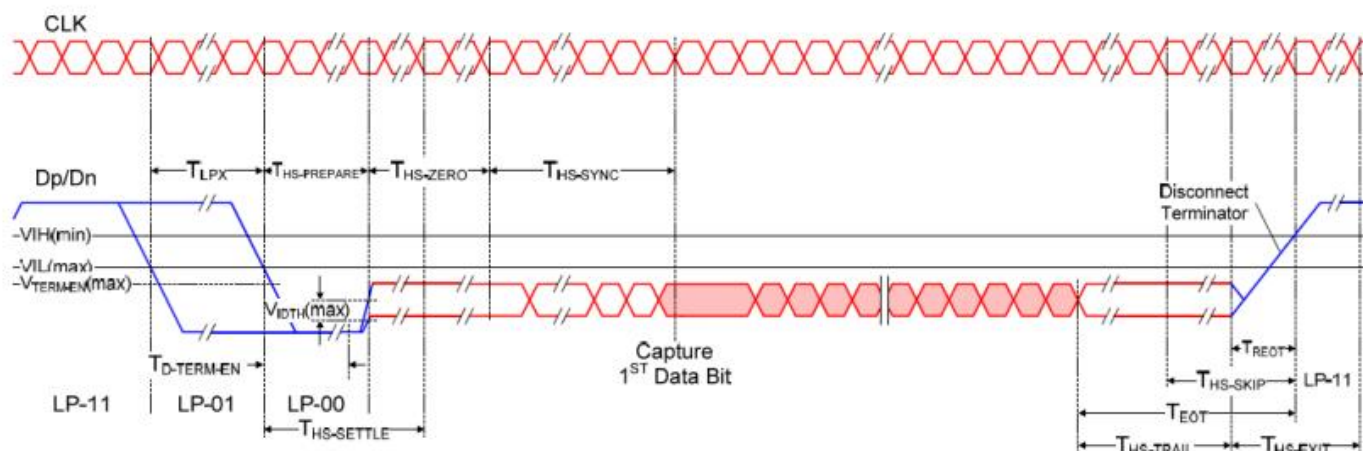


High Speed Clock Transmission

Parameter	Symbol	Min	Typ	Max	Units
Time that the transmitter shall continue sending HS clock after the last associated Data Lane has transitioned to LP mode	TCLK-POST	60+52UI	-	-	ns
Detection time that the clock has stopped toggling	TCLK-MISS	-	-	60	ns
Time to drive LP-00 to prepare for HS clock transmission	TCLK-PREPARE	38	-	95	ns
Minimum lead HS-0 drive period before starting clock	TCLK-PREPARE + TCLK-ZERO	300	-	-	ns
Time to enable Clock Lane receiver line termination measured from when Dn cross $V_{IL,MAX}$	THS-TERM-EN	-	-	38	ns
Minimum time that the HS clock must be prior to any associated data lane beginning the transmission from LP to HS mode	TCLK-PRE	8	-	-	UI
Time to drive HS differential state after last payload clock bit of a HS transmission burst	TCLK-TRAIL	60	-	-	ns



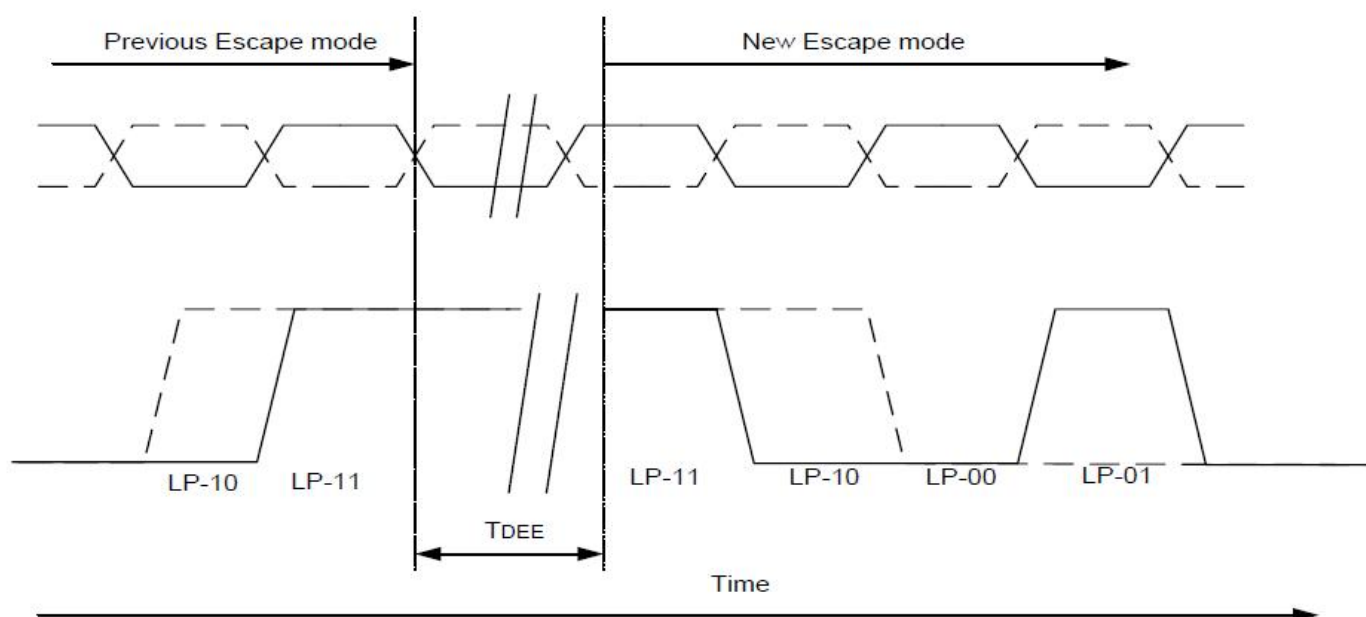
High Speed Data Transmission in Bursts



LP11 timing request between data transformation

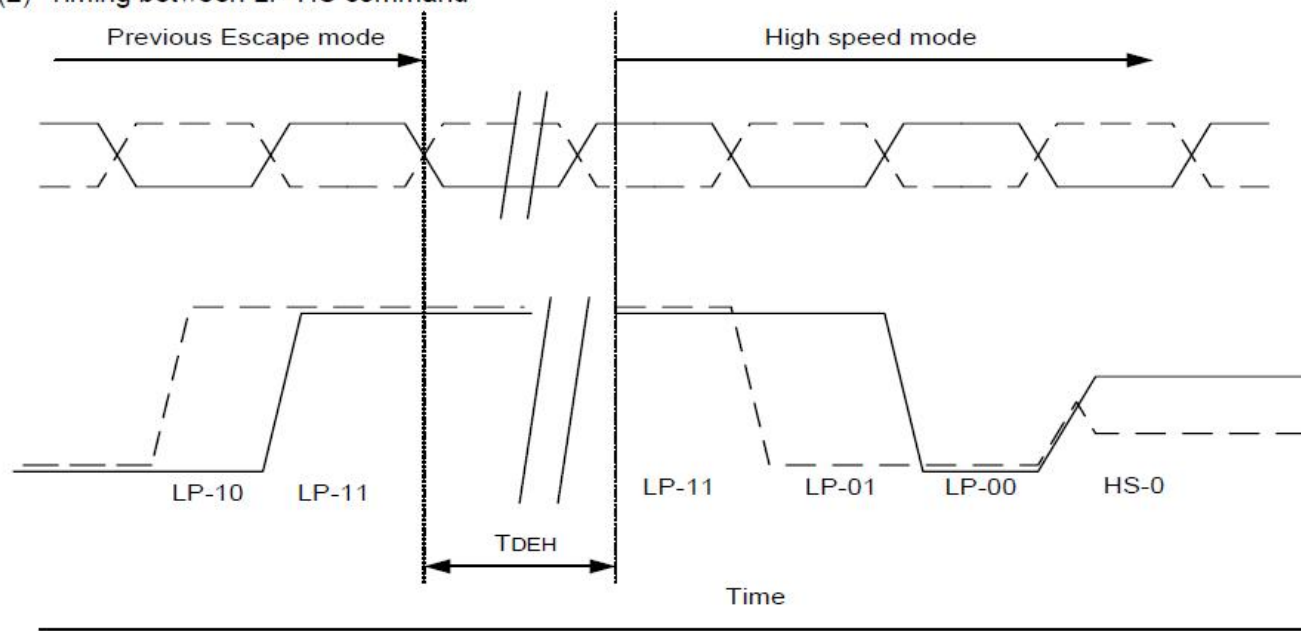
When Clock lane of DSI TX chip always keeps High speed mode, then Clock lane never go back to Low power mode. If Date lane of TX chip needs to transmit the next new data transmission or sequence, after the end of Low power mode or High speed mode or BTA. Then TX chip needs to keep LP-11 stop state before the next new data transmission, no matter in Low power mode or High speed mode or BTA. The LP-11 minimum timing is required for RX chip in the following 9 conditions, include of LP-LP, LP-HS, HS-LP, HS-HS, BTA-BTA, LP-BTA, BTA-LP, HS-BTA, and BTA-HS. This rule is suitable for short or long packet between TX and RX data transmission.

(1) Timing between LP-LP command



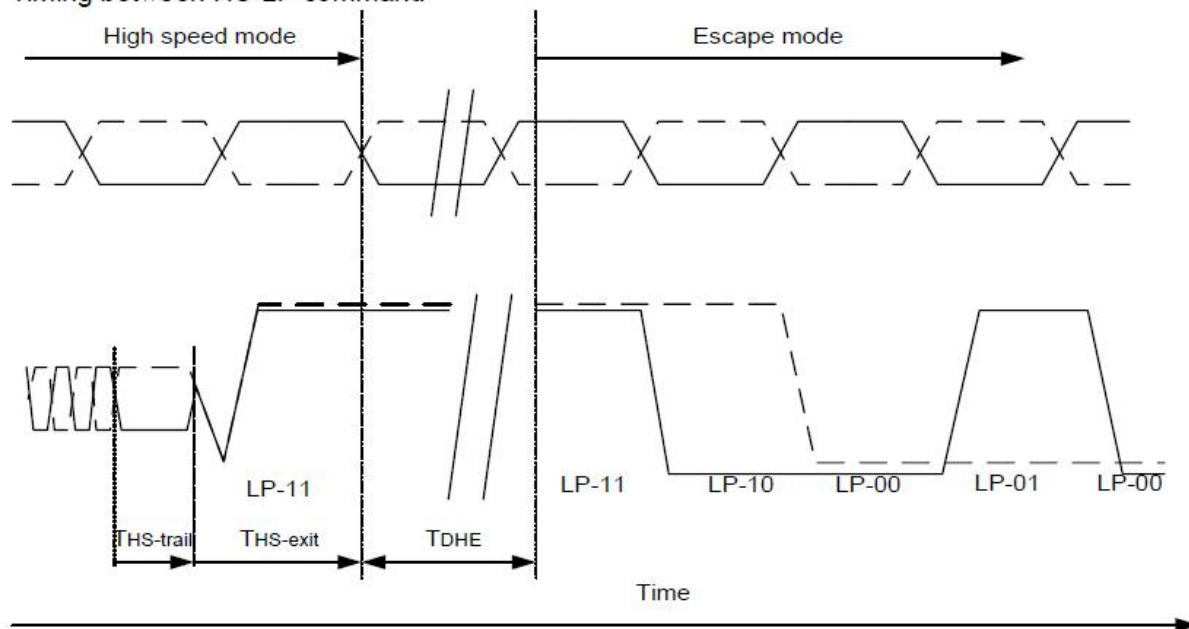
Parameter	Symbol	Min	Typ	Max	Unit
LP-11 delay to start of the new Escape Mode Entry	TDEE	150	-	-	ns

(2) Timing between LP-HS command



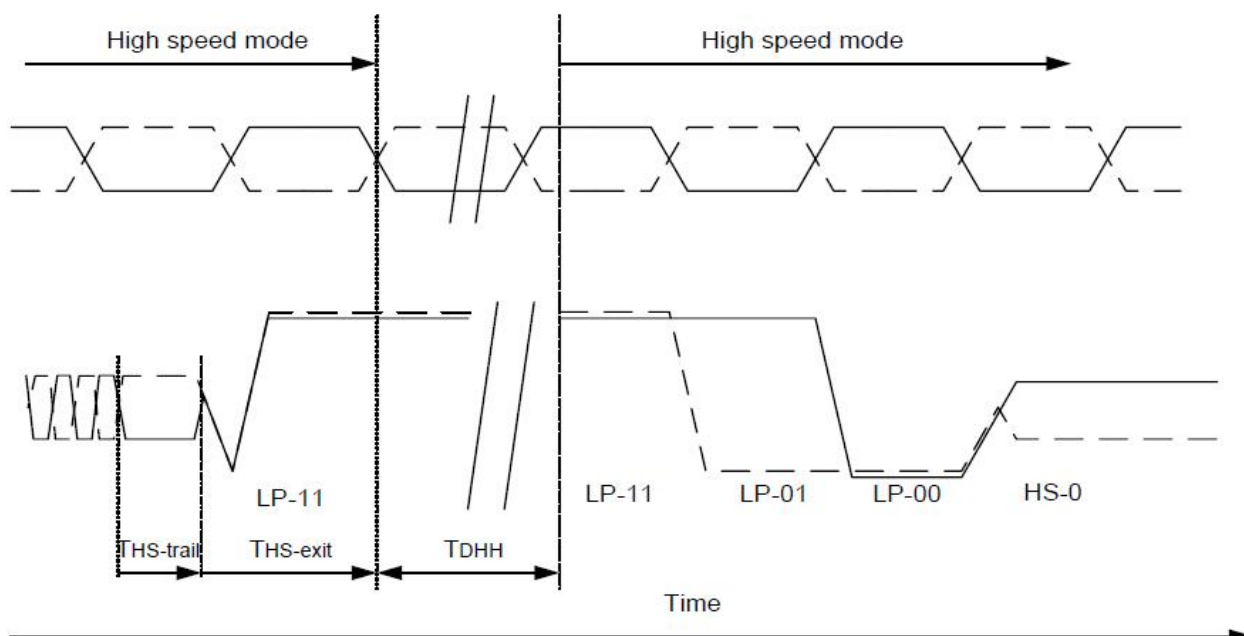
Parameter	Symbol	Min	Typ	Max	Unit
LP-11 delay to start of the Entering High Speed Mode	TDEH	Max(150,32UI)	-	-	ns

(3) Timing between HS-LP command



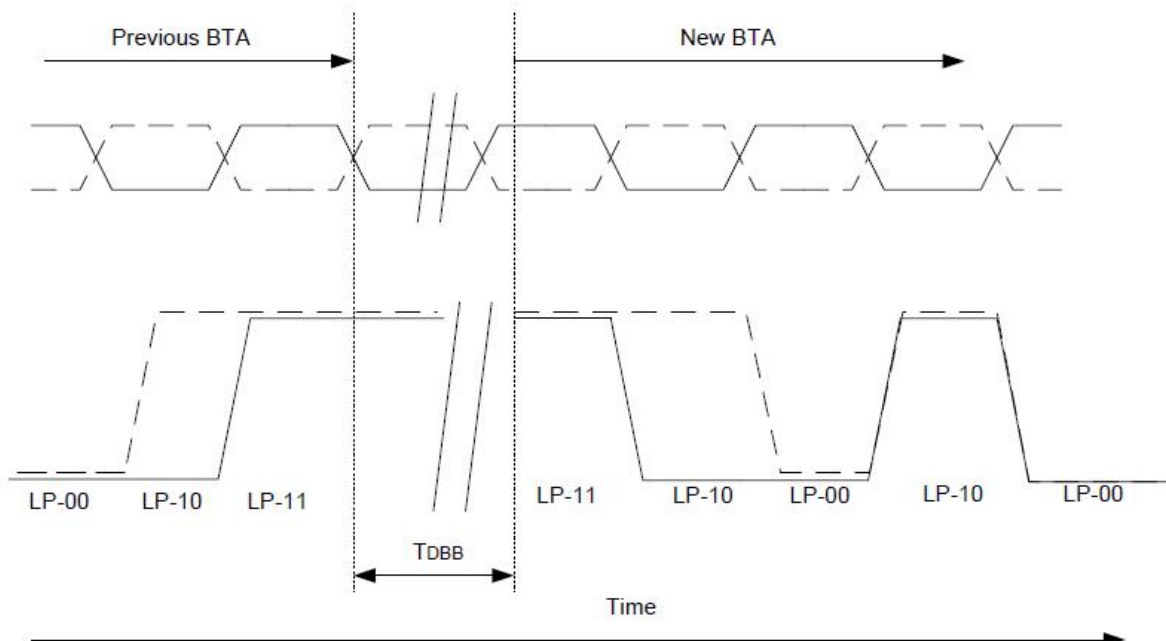
Parameter	Symbol	Min	Typ	Max	Unit
LP-11 delay to start of the Escape Mode Entry	TDHE	Max(150,32UI)	-	-	ns

(4) Timing between HS-HS command



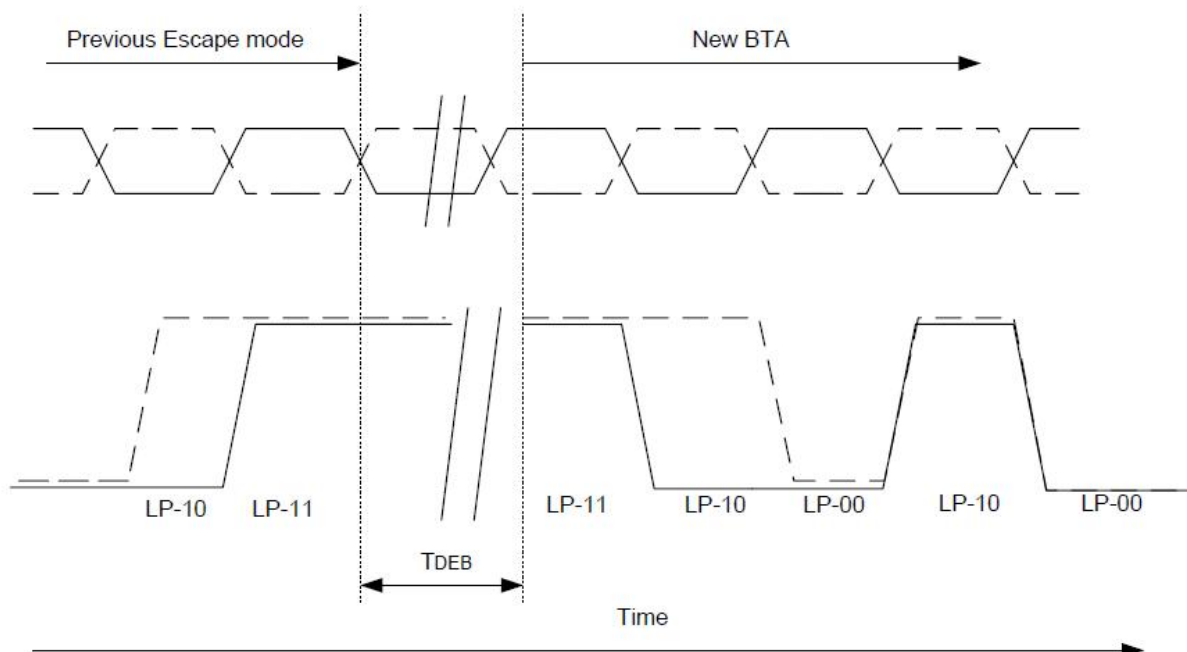
Parameter	Symbol	Min	Typ	Max	Unit
LP-11 delay to start of the Entering High Speed Mode	TDHH	Max(150,32UI)	-	-	ns

(5) Timing between BTA-BTA command



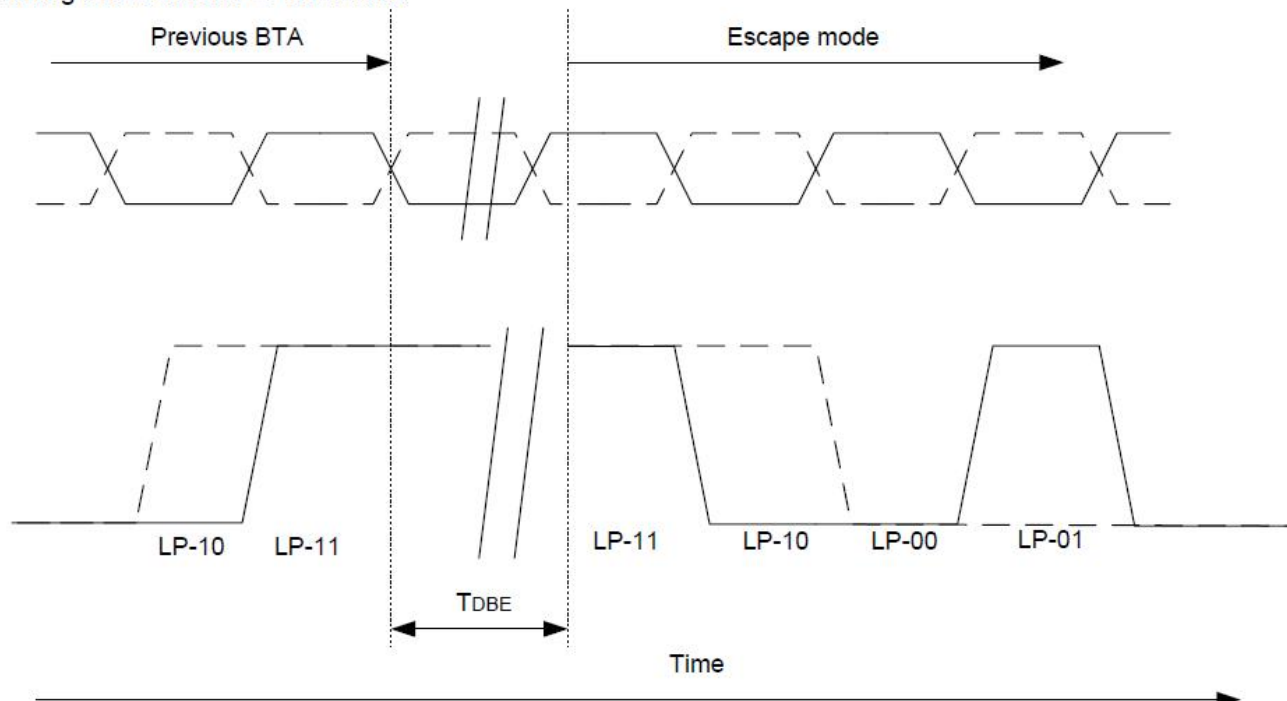
Parameter	Symbol	Min	Typ	Max	Unit
LP-11 delay to start of the new BTA	TDBB	150	-	-	ns

(6) Timing between LP-BTA command



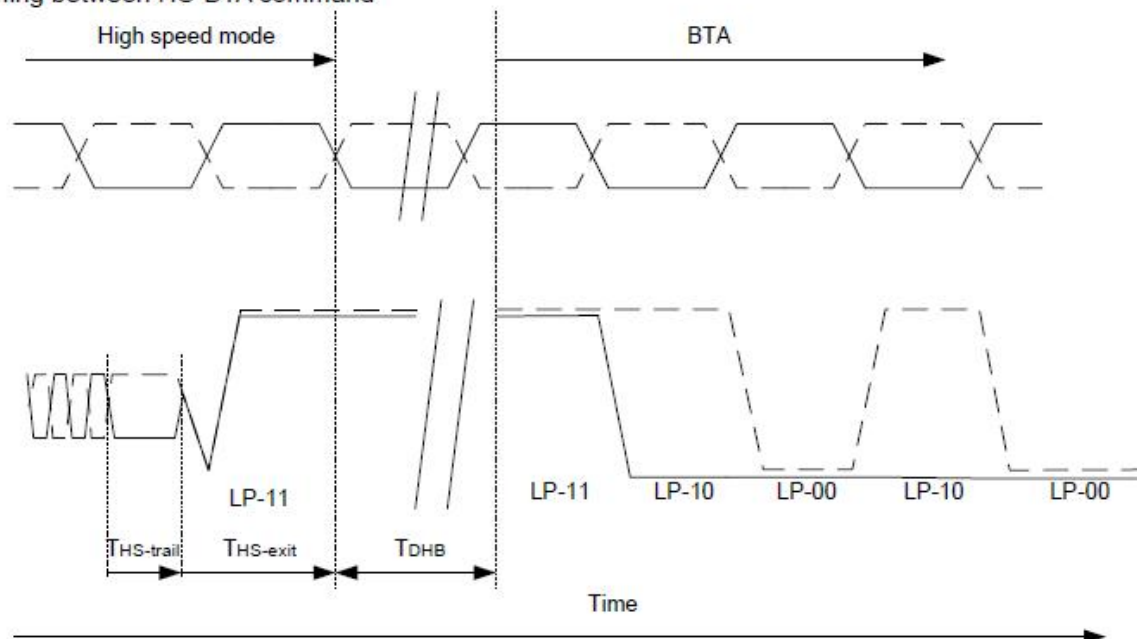
Parameter	Symbol	Min	Typ	Max	Unit
LP-11 delay to start of the new BTA	TDEB	150	-	-	ns

(7) Timing between BTA-LP command



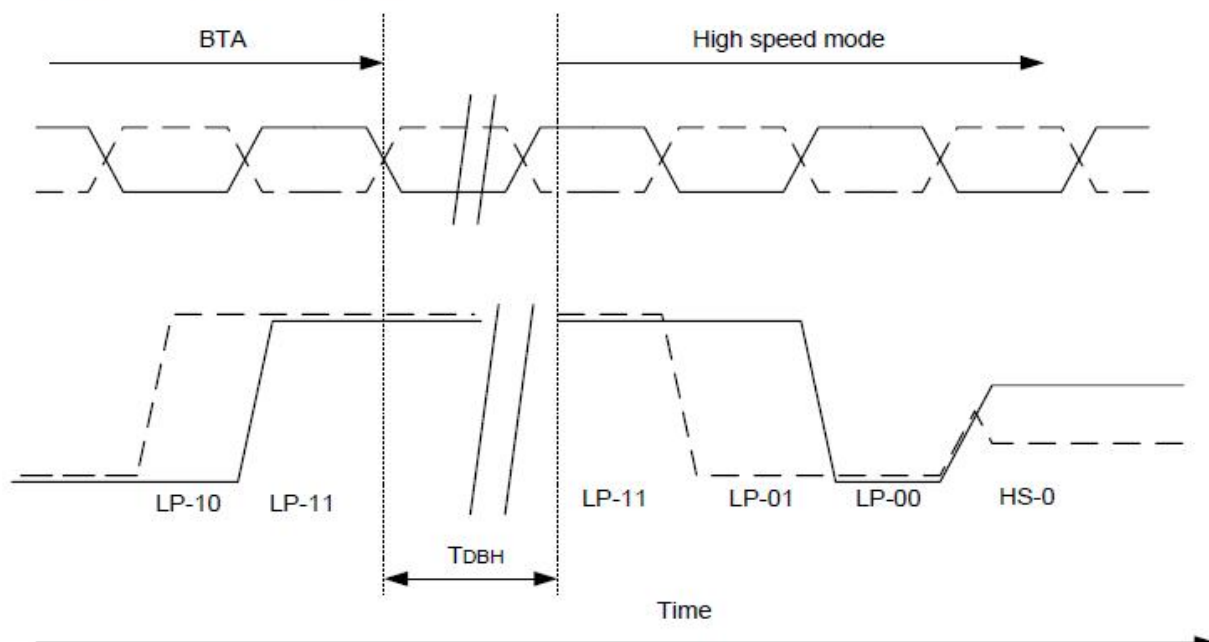
Parameter	Symbol	Min	Typ	Max	Unit
LP-11 delay to start of the Escape Mode Entry	TDBE	150	-	-	ns

(8) Timing between HS-BTA command



Parameter	Symbol	Min	Typ	Max	Unit
LP-11 delay to start of the BTA	T _{DHB}	Max(150,32UI)	-	-	ns

(9) Timing between BTA-HP command



Parameter	Symbol	Min	Typ	Max	Unit
LP-11 delay to start of the Entering High Speed Mode	T _{DHB}	Max(150,32UI)	-	-	ns

5.3 Input Timing Table (4Lane)

DE mode

Parameter	Symbol	Value			Unit
		Min.	Typ.	Max.	
DCLK frequency @Frame rate=60hz	fclk	40.8	51.2	67.2	Mhz
Horizontal display area	thd	1024			DCLK
HSYNC period time	th	1114	1344	1400	DCLK
HSYNC blanking	thb+thfp	90	320	376	DCLK
Vertical display area	Tvd	600			H
VSYNC period time	Tv	610	635	800	H
VSYNC blanking	Tvb+Tvfp	10	35	200	H

HV mode

Horizontal input timing

Parameter		Symbol	Value			Unit
Horizontal display area		thd	1024			DCLK
DCLK frequency@ Frame rate=60hz		fclk	Min.	Typ.	Max.	Mhz
			44.9	51.2	63	
1 Horizontal Line		th	1200	1344	1400	DCLK
HSYNC pulse width	Min.	thpw	1			
	Typ.		70			
	Max.		140			
HSYNC blanking		thb	160	160	160	
HSYNC front porch		thfp	16	160	216	

HV mode

Vertical input timing

Parameter	Symbol	Value			Unit
		Min.	Typ.	Max.	
Vertical display area	tvd	600			H
VSYNC period time	tv	624	635	750	H
VSYNC pulse width	tvpw	1	10	20	H
VSYNC back porch	tvb	23	23	23	H
VSYNC front porch	tvfp	1	12	127	H

6. Optical Specifications

Item	Symbol	Condition	Min.	Typ.	Max.	Unit	Note
Viewing Angle (CR≥10) B/L ON	θ_T	$\Phi=90^\circ$ (12 o'clock)	80	-	-	deg	Note2
	θ_B	$\Phi=270^\circ$ (6 o'clock)	80	-	-	deg	Note2
	θ_L	$\Phi=180^\circ$ (9 o'clock)	80	-	-	deg	Note2
	θ_R	$\Phi=0^\circ$ (3 o'clock)	80	-	-	deg	Note2
Response Time	T_{ON}	Normal $\theta=\Phi=0^\circ$	-	12	17	msec	Note4
	T_{OFF}		-	12	17	msec	Note4
Contrast Ratio	CR		800	1000	-	-	Note1 Note3
Color Chromaticity	W_X		0.2781	0.3081	0.3381	-	Note1 Note5
	W_Y		0.2901	0.3201	0.3501	-	Note1 Note5
Luminance	L		370	420	-	cd/m ²	Note1 Note7
Luminance Uniformity	Y_U		75	80	-	%	Note1 Note6
NTSC	-		45	50	-	%	-

Note 1: Definition of optical measurement system

The optical characteristics should be measured in dark room. After 5 minutes operation, the optical properties are measured at the center point of the LCD screen. All input terminals LCD panel must be ground when measuring the center area of the panel.

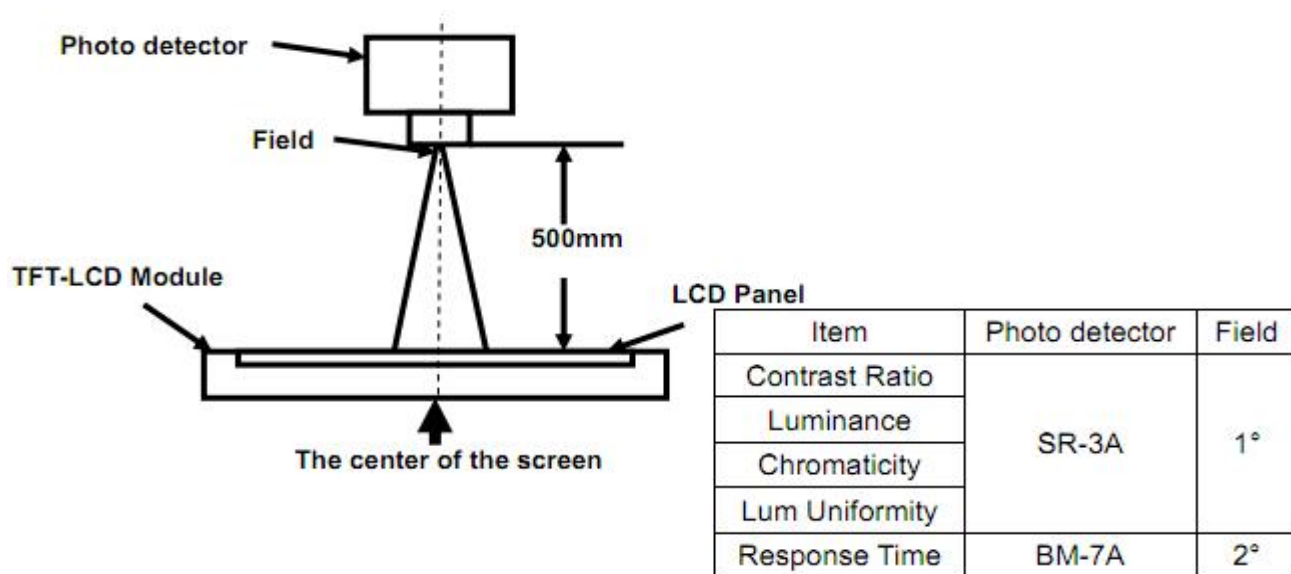


Fig 1

Note 2: Definition of viewing angle range and measurement system.

viewing angle is measured at the center point of the LCD by CONOSCOPE(ergo-80).

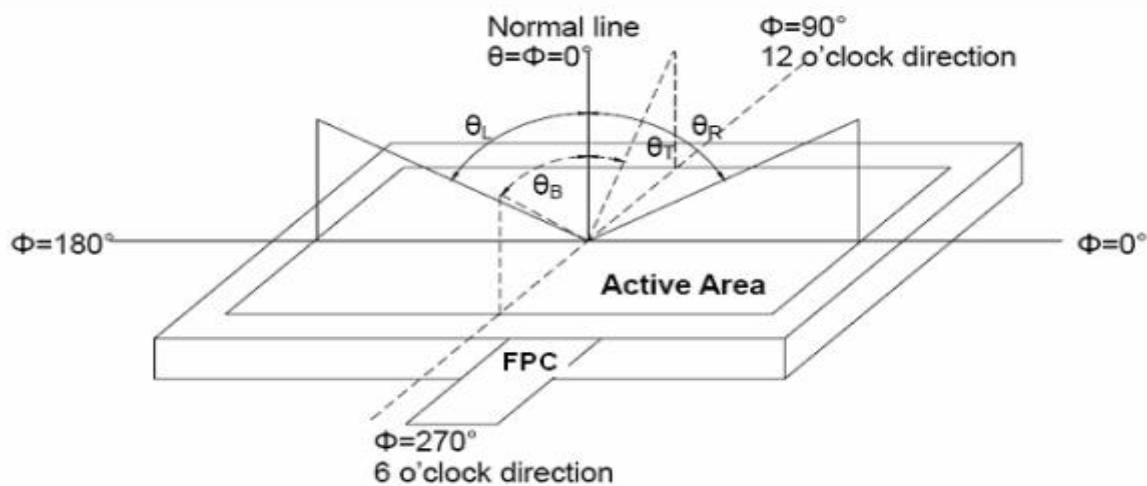


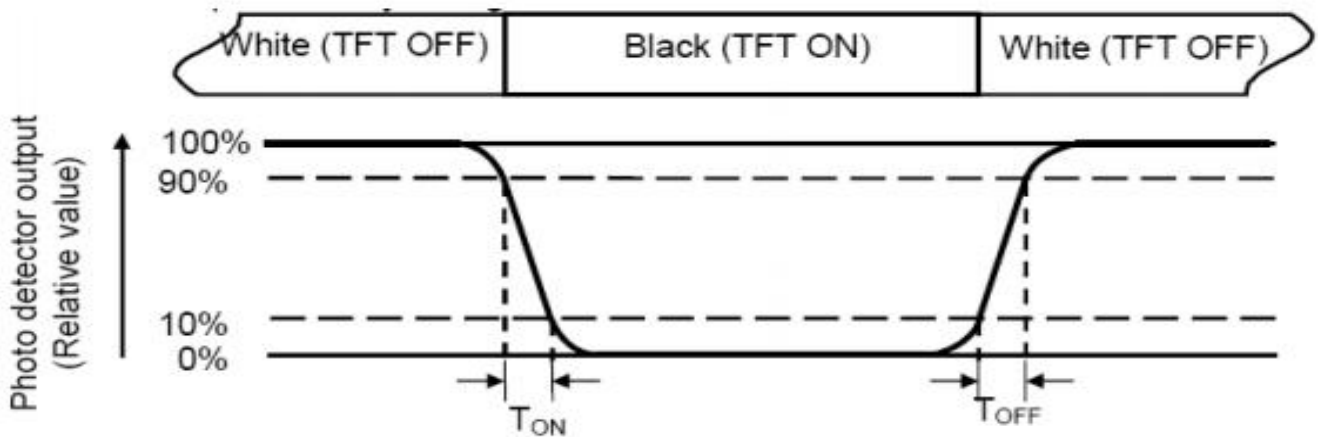
Fig 2 Definition of viewing angle

Note 3: Definition of contrast ratio

$$CR = \frac{\text{Luminance with all pixels white}}{\text{Luminance with all pixels black}}$$

Note 4: Definition of Response time

The response time is defined as the LCD optical switching time interval between “White” state and “Black” state. Rise time (TON) is the time between photo detector output intensity changed from 90% to 10%. And fall time (TOFF) is the time between photo detector output intensity changed from 10% to 90%.



Note 5: Definition of color chromaticity (CIE1931)

Color coordinates measured at center point of LCD.

Note 6: Definition of Luminance Uniformity

The luminance uniformity in surface luminance is determined by measuring luminance at each test position 1 through n, and then dividing the maximum luminance of n points luminance by minimum luminance of n points luminance. For more information see FIG.3-a/b

Note 7: Surface luminance is the luminance with all pixels displaying white.

L_v = Average Surface Luminance with all white pixels ($P_1, P_2, P_3, \dots, P_n$)

For more information see FIG.3-a/b

Note 8:

H,V : Active area(see Figure b)

Light spot size $\varnothing = 5\text{mm}$ (BM-5) or $\varnothing = 7.7\text{mm}$ (BM-7) 50cm distance or compatible distance from the LCD surface to detector lens. test spot position : see Figure b.

measurement instrument : TOPCON's luminance meter SR-3A or BM-7 or compatible (see Figure 1).

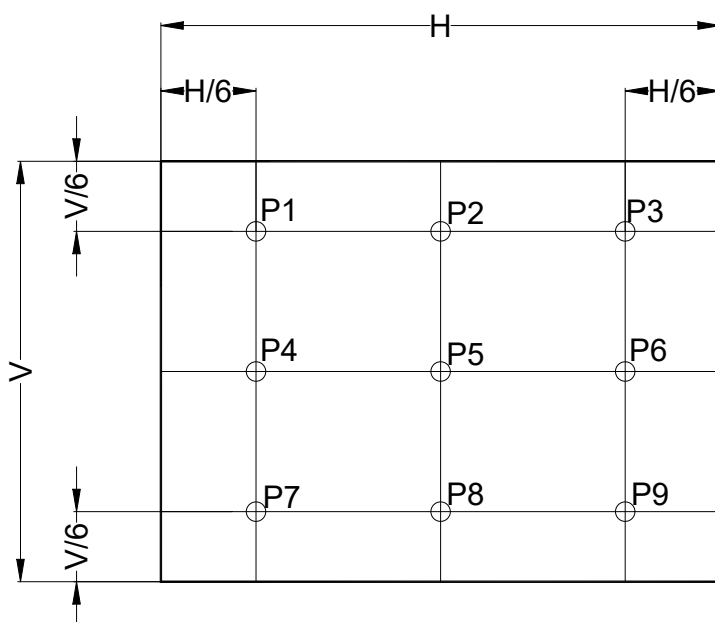


Fig. 3-b Definition of points

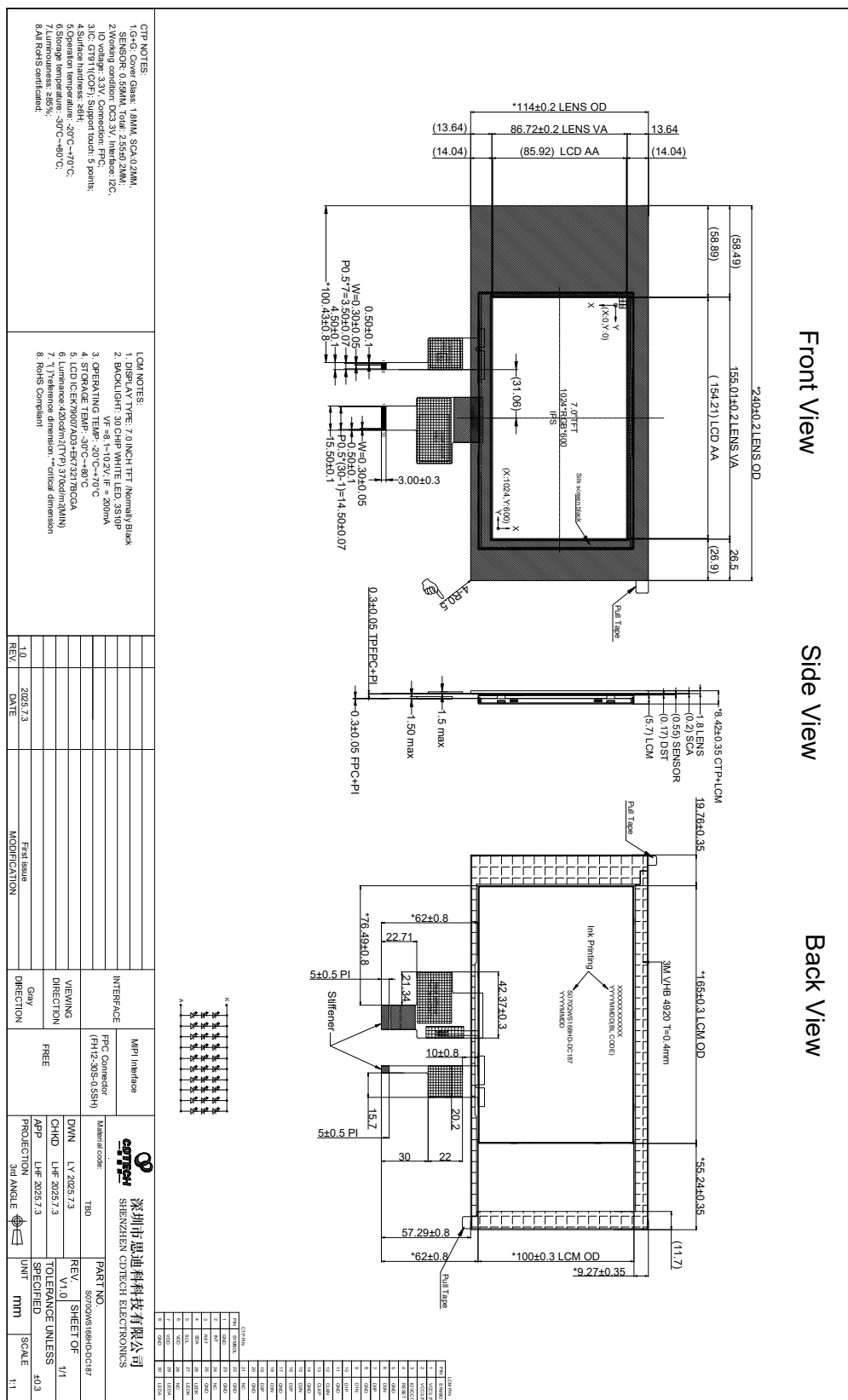
7. Reliability Test Items

Test Item	Test Conditions
High Temperature Storage	Ta= +80℃ 96hrs
Low Temperature Storage	Ta= -30℃ 96hrs
High Temperature Operation	Ta= +70℃ 96hrs
Low Temperature Operation	Ta= -20℃ 96hrs
High Temperature and Humidity Storage	Ta= +60℃, 90% RH 96hrs
Thermal Shock (Non-operation)	-30℃/30 min ~ +80℃/30 min for 20 cycles Start with cold temperature end with high temperature
Electro Static Discharge	Contact = ± 4 kV, class B Air = ± 8 kV, class B R=330Ω,C=150pF
Vibration	Sweep: 10Hz~55Hz~10Hz Stroke: 1.5mm 2 hrs for each direction of X .Y. Z.
Mechanical Shock	60G 6ms,±X,±Y,±Z 3 times for each direction
Package Drop Test	Height: 60 cm 1 corner, 3 edges, 6 surfaces

Notes: The test result shall be evaluated after the sample has been left at room temperature and humidity for 2 hours without load. No condensation shall be accepted. The sample will not be accepted if appear these defects:

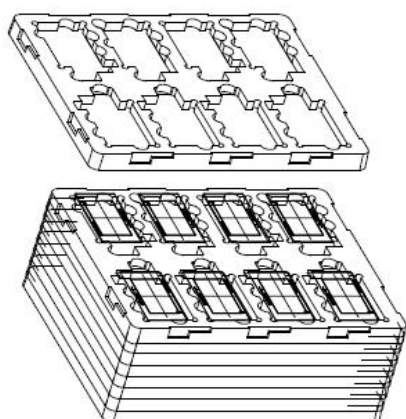
- 1). Air bubble in the LCD
- 2). Seal leak or Glass crack
- 3). Non display or abnormal display
- 4). Brightness reduction >50%

8. Mechanical Drawing

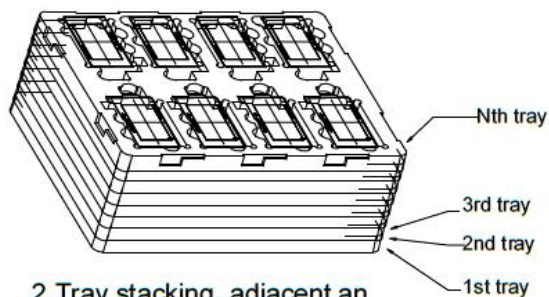


9. Packing

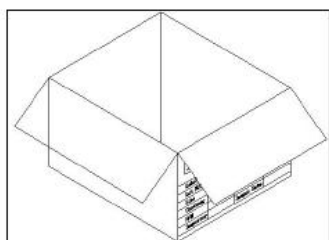
Packing Method



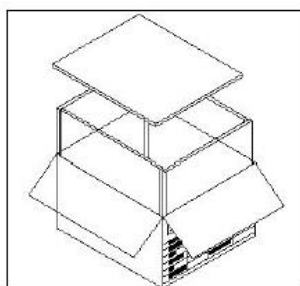
1. Put LCD module into tray cavity



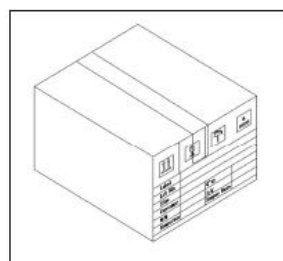
2. Tray stacking, adjacent an upper lower layer with a 180-degree rotation



4. put the tray stack into carton



5. 6 sides of white foams inside the box



6. Carton sealing with adhesive tape

10. Precautions for Use of LCD modules

10.1 Handling Precautions

10.1.1. The display panel is made of glass. Do not subject it to a mechanical shock by dropping it from a high place, etc.

10.1.2. If the display panel is damaged and the liquid crystal substance inside it leaks out, be sure not to get any in your mouth, if the substance comes into contact with your skin or clothes, promptly wash it off using soap and water.

10.1.3. Do not apply excessive force to the display surface or the adjoining areas since this may cause the color tone to vary.

10.1.4. The polarizer covering the display surface of the LCD module is soft and easily scratched. Handle this polarizer carefully.

10.1.5. If the display surface is contaminated, breathe on the surface and gently wipe it with a soft dry cloth. If still not completely clear, moisten cloth with one of the following solvents:

- Isopropyl alcohol
- Ethyl alcohol

Solvents other than those mentioned above may damage the polarizer. Especially, do not use the following:

- Water
- Ketene
- Aromatic solvents

10.1.6. Do not attempt to disassemble the LCD Module.

10.1.7. If the logic circuit power is off, do not apply the input signals.

10.1.8. To prevent destruction of the elements by static electricity, be careful to maintain an optimum work environment.

10.1.8.1. Be sure to ground the body when handling the LCD Modules.

10.1.8.2. Tools required for assembly, such as soldering irons, must be properly ground.

10.1.8.3. To reduce the amount of static electricity generated, do not conduct assembly and other work under dry conditions.

10.1.8.4. The LCD Module is coated with a film to protect the display surface. Be care when peeling off this protective film since static electricity may be generated.

10.2 Storage Precautions

10.2.1. When storing the LCD modules, avoid exposure to direct sunlight or to the light of fluorescent lamps.

10.2.2. The LCD modules should be stored under the storage temperature range if the LCD modules will be stored for a long time, the recommend condition is :

Temperature : 0℃ ~40℃ Relatively humidity: ≤80%

10.2.3. The LCD modules should be stored in the room without acid, alkali and harmful gas.

10.3 Transportation Precautions

The LCD modules should be no falling and violent shocking during transportation, and also should avoid excessive press, water, damp and sunshine.

10.4 Packaging instructions

When the customers using trays, they have to stack the adjacent trays in a 180° staggered to prevent pressure that could cause product damage.